

FFPF08S60ST

8 A, 600 V STEALTH™ II Diode

Features

- Stealth Recovery $t_{rr} = 30$ ns (@ $I_F = 8$ A)
- Max Forward Voltage, $V_F = 3.4$ V (@ $T_C = 25^\circ\text{C}$)
- 600 V Reverse Voltage and High Reliability
- RoHS Compliant

Applications

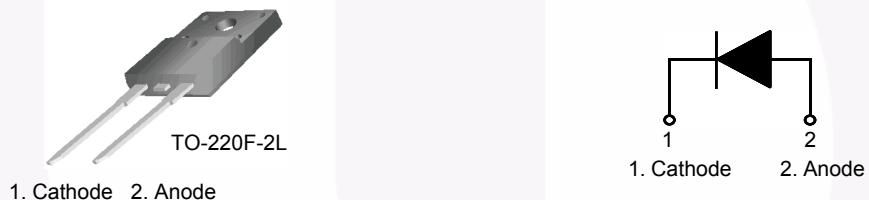
- General Purpose
- SMPS
- Boost Diode in Continuous Mode Power Factor Corrections
- Power Switching Circuits

Description

The FFPF08S60S is STEALTH™ II diode with soft recovery characteristics. It is silicon nitride passivated ion-implanted epitaxial planar construction.

This device is intended for use as freewheeling of boost diode in switching power supplies and other power switching applications. Their low stored charge and hyperfast soft recovery minimize ringing and electrical noise in many power switching circuits reducing power loss in the switching transistors.

Pin Assignments



Absolute Maximum Ratings

$T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Value	Unit
V_{RRM}	Peak Repetitive Reverse Voltage	600	V
V_{RWM}	Working Peak Reverse Voltage	600	V
V_R	DC Blocking Voltage	600	V
$I_{F(AV)}$	Average Rectified Forward Current @ $T_C = 95^\circ\text{C}$	8	A
I_{FSM}	Non-repetitive Peak Surge Current 60Hz Single Half-Sine Wave	80	A
T_J, T_{STG}	Operating Junction and Storage Temperature	- 65 to +150	°C

Thermal Characteristics

$T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Max.	Unit
$R_{\theta JC}$	Maximum Thermal Resistance, Junction to Case	3.4	°C/W

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FFPF08S60STTU	FFPF08S60ST	TO-220F-2L	Tube	N/A	N/A	50

Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Conditions	Min.	Typ.	Max	Unit
V_F^1	$I_F = 8\text{ A}$ $I_F = 8\text{ A}$	$T_C = 25^\circ\text{C}$	-	2.1	V
		$T_C = 125^\circ\text{C}$	-	1.6	V
I_R^1	$V_R = 600\text{ V}$ $V_R = 600\text{ V}$	$T_C = 25^\circ\text{C}$	-	-	μA
t_{rr} I_{rr} S factor Q_{rr}	$I_F = 8\text{ A}$, $di_F/dt = 200\text{ A}/\mu\text{s}$, $V_R = 390\text{ V}$	$T_C = 25^\circ\text{C}$	-	100	μA
		$T_C = 125^\circ\text{C}$	-	500	μA
		$T_C = 25^\circ\text{C}$	-	25	ns
		$T_C = 25^\circ\text{C}$	-	19	ns
t_{rr} I_{rr} S factor Q_{rr}	$I_F = 8\text{ A}$, $di_F/dt = 200\text{ A}/\mu\text{s}$, $V_R = 390\text{ V}$	$T_C = 25^\circ\text{C}$	-	2.2	A
		$T_C = 25^\circ\text{C}$	-	0.6	-
		$T_C = 25^\circ\text{C}$	-	21	nC
		$T_C = 125^\circ\text{C}$	-	58	ns
t_{rr} I_{rr} S factor Q_{rr}	$I_F = 8\text{ A}$, $di_F/dt = 200\text{ A}/\mu\text{s}$, $V_R = 390\text{ V}$	$T_C = 125^\circ\text{C}$	-	4.3	A
		$T_C = 125^\circ\text{C}$	-	1.3	-
		$T_C = 125^\circ\text{C}$	-	125	nC
W_{AVL}	Avalanche Energy ($L = 40\text{ mH}$)	20	-	-	mJ

Notes:

1. Pulse : Test Pulse width = 300 μs , Duty Cycle = 2%

Test Circuit and Waveforms

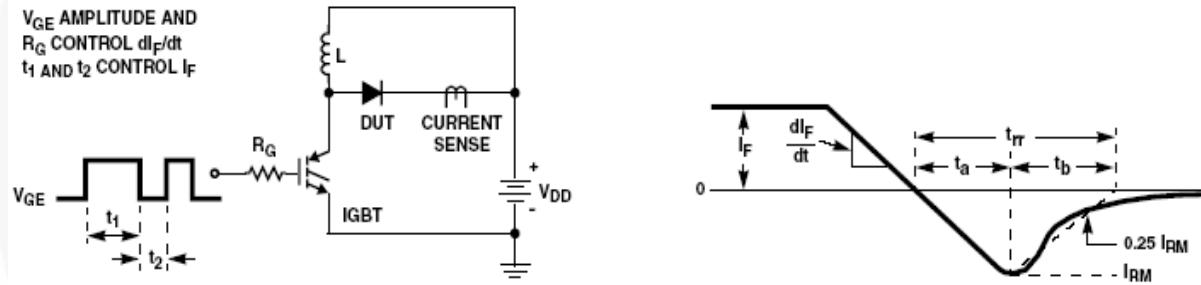


Figure 1. Diode Reverse Recovery Test Circuit & Waveform

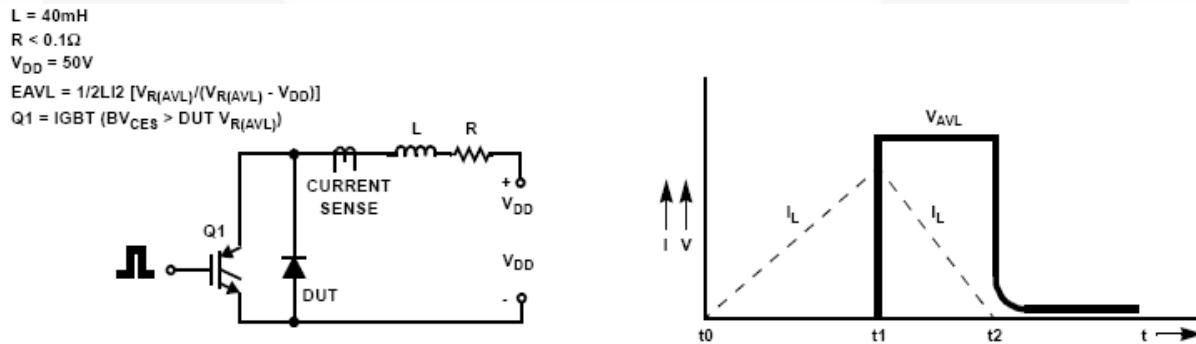


Figure 2. Unclamped Inductive Switching Test Circuit & Waveform

Typical Performance Characteristics $T_c = 25^\circ\text{C}$ unless otherwise noted

Figure 3. Typical Forward Voltage Drop

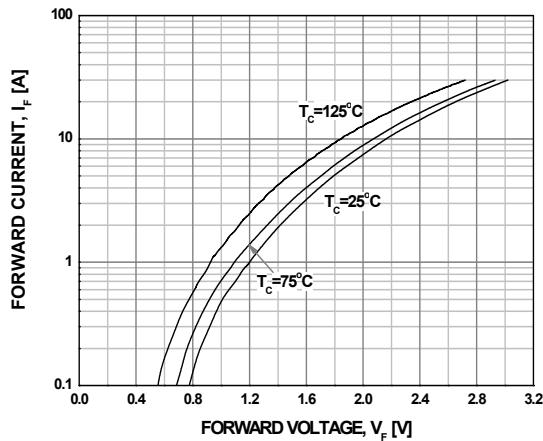


Figure 4. Typical Reverse Current

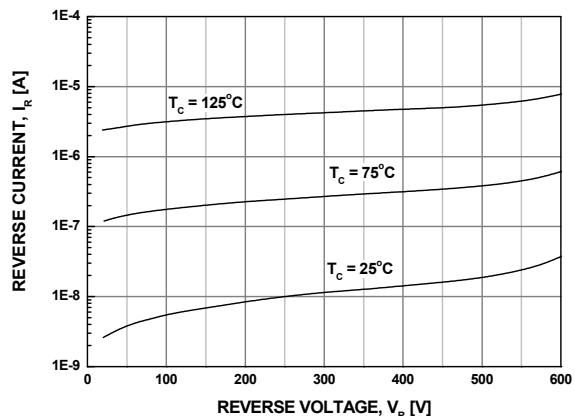


Figure 5. Typical Junction Capacitance

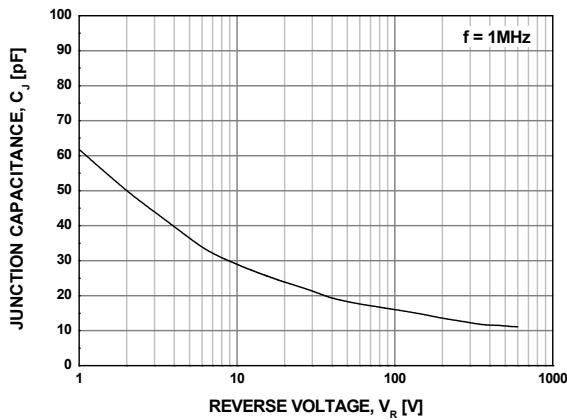


Figure 6. Typical Reverse Recovery Time

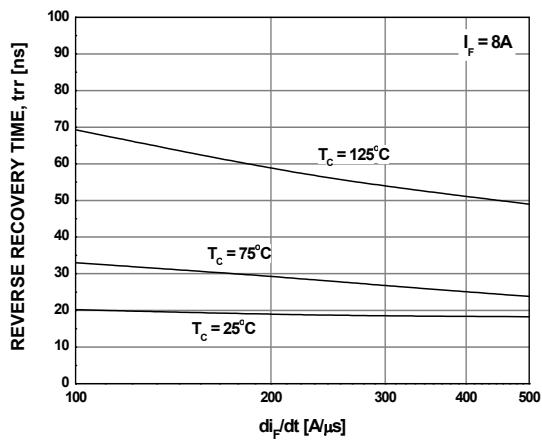


Figure 7. Typical Reverse Recovery Current

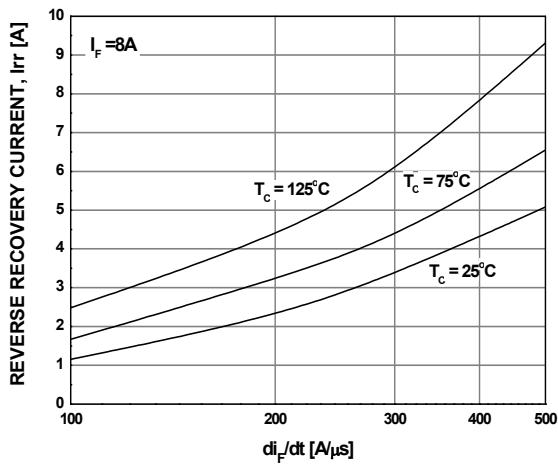
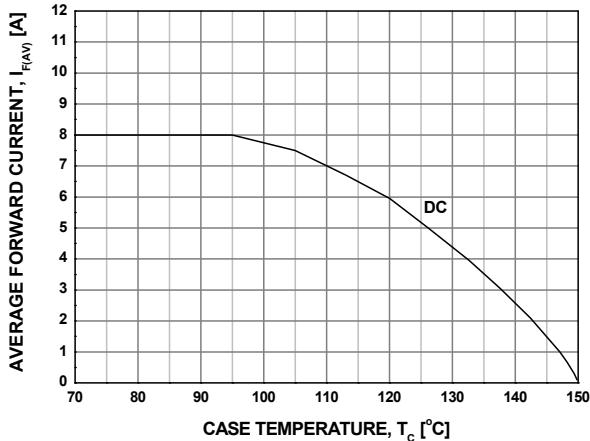
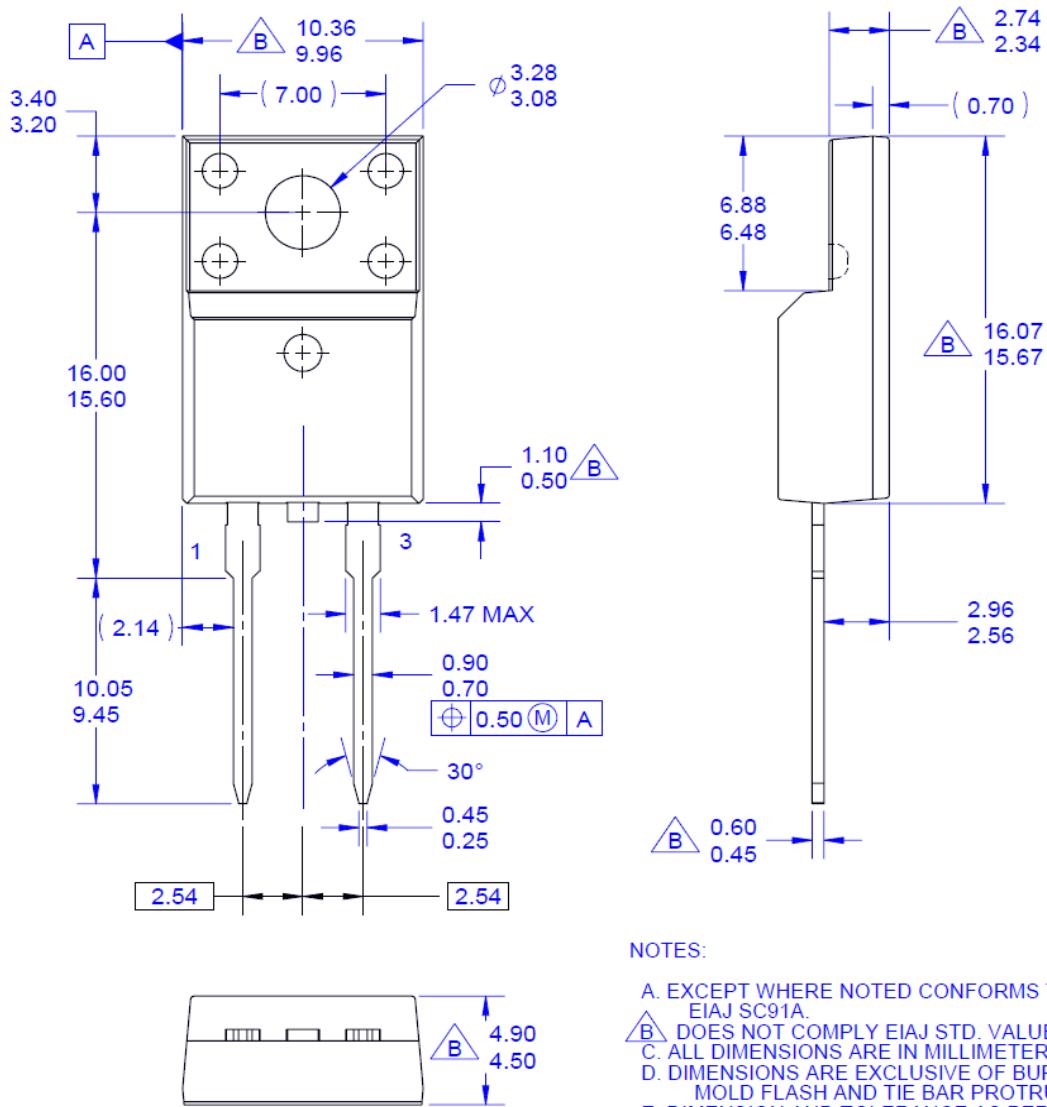


Figure 8. Forward Current Deration Curve



Mechanical Dimensions



NOTES:

- A. EXCEPT WHERE NOTED CONFORMS TO EIAJ SC91A.
- B. DOES NOT COMPLY EIAJ STD. VALUE.
- C. ALL DIMENSIONS ARE IN MILLIMETERS.
- D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
- E. DIMENSION AND TOLERANCE AS PER ASME Y14.5-1994.
- F. DRAWING FILE NAME: TO220C02REV2

Figure 9. TO-220F 2L - 2LD; TO220; MOLDED; FULL PACK

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